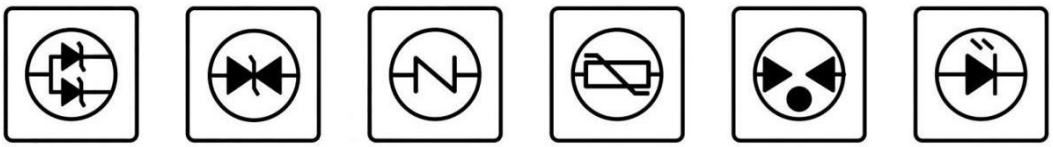
MSKSEMI 美森科
SEMICONDUCTOR



SM320A-MS THRU SM3100A-MS

Product specification

SM320A-MS THRU SM3100A-MS

Features

- For Surface Mounted Applications
- High Temperature Metallurgically Bonded Contacts
- Plastic Material - UL Flammability Classification 94V-0
- High Reliability
- High Current Capability and Low VF
- Submersible Temperature of 265C for 10 Seconds in Solder Bath

MECHANICAL DATA

- Case: SMA/DO-214AC, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Weight: 0.064 grams (approx.)

Reference News

PACKAGE OUTLINE

SMA(DO-214AC)

Marking

SM320A-MS	SM330A-MS	SM340A-MS	SM350A-MS
S32 *	S33 *	S34 *	S35 *
SM360A-MS	**SM380A-MS**	**SM390A-MS**	**SM3100A-MS**
S36 *	S38 *	S39 *	S310 *

Maximum Ratings and Electrical Characteristics

T_A = 25℃ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	SM320A-MS	SM330A-MS	SM340A-MS	SM350A-MS	SM360A-MS	SM380A-MS	SM390A-MS	SM3100A-MS	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	20	30	40	50	60	80	90	100	V
RMS Reverse Voltage	$V_{R(RMS)}$	14	21	28	35	42	56	64	71	V
Average Rectified Output Current @T_L = 105°C	I_O	3.0								A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	100								A
Forward Voltage @I_F = 3.0A	V_{FM}	0.55			0.75		0.85			V
Peak Reverse Current @T_A = 25°C At Rated DC Blocking Voltage @T_A = 100°C	I_{RM}	2.0 20								mA
Typical Thermal Resistance (Note 1)	$R_{\theta JL}$ $R_{\theta JA}$	10 50								°C/W
Operating Temperature Range	T_j	-65 to +125								°C
Storage Temperature Range	T_{STG}	-65 to +150								°C

Note: 1. Mounted on P.C. Board with 8.0mm^2 copper pad area.

RATINGS AND CHARACTERISTIC CURVES SM320A-MS THRU SM3100A-MS

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

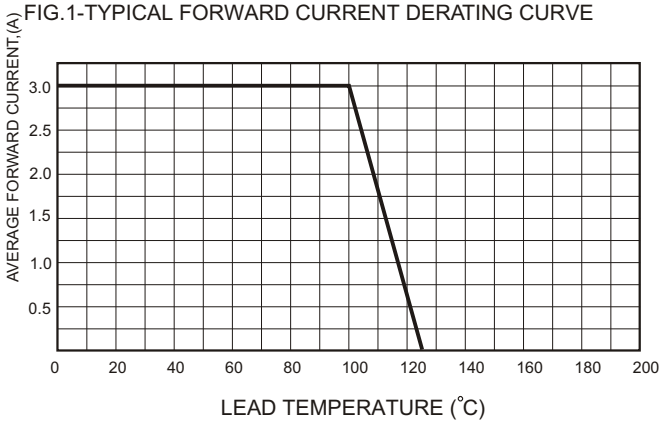


FIG.2-TYPICAL FORWARD CHARACTERISTICS

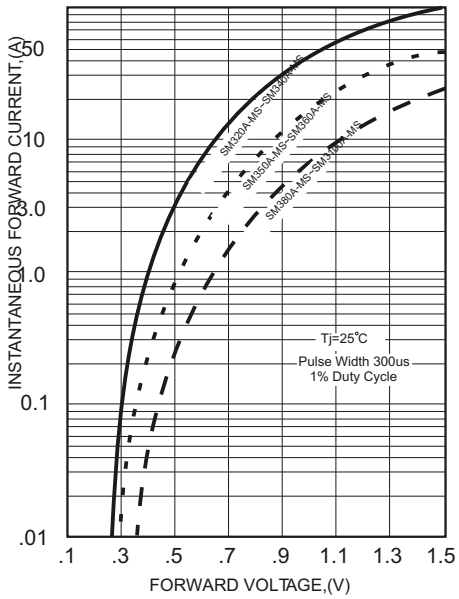


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

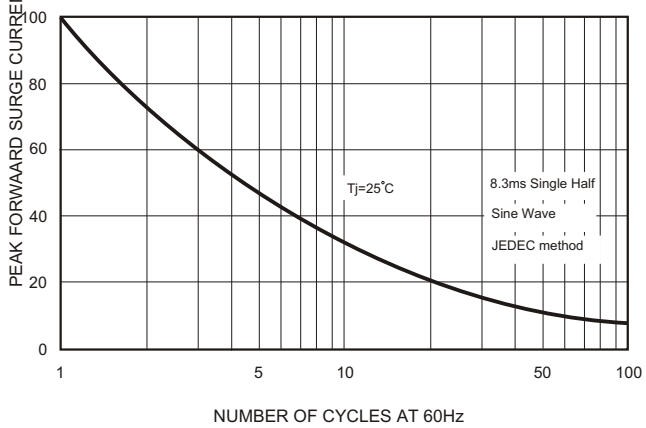


FIG.4-TYPICAL JUNCTION CAPACITANCE

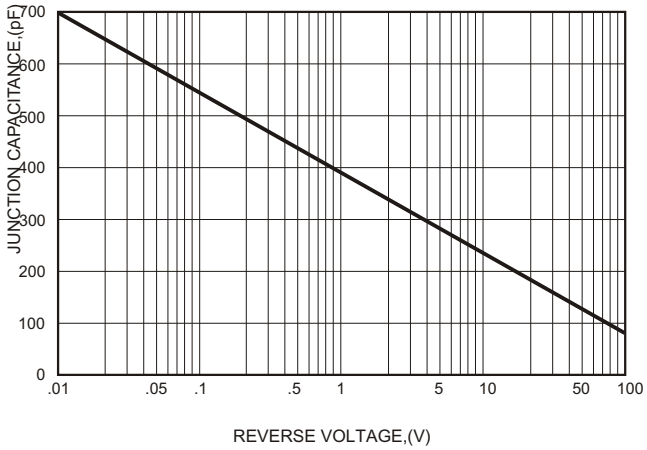
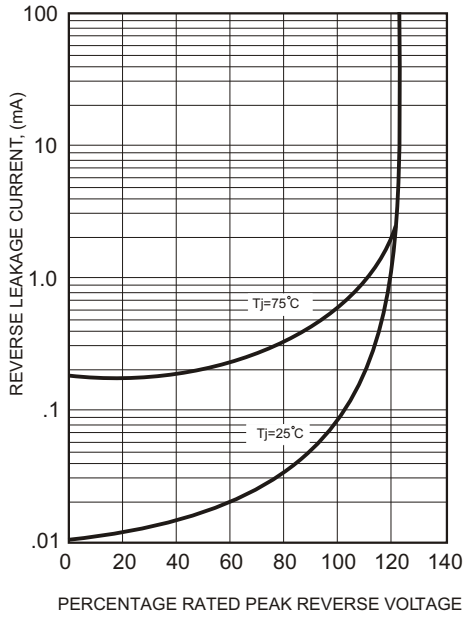
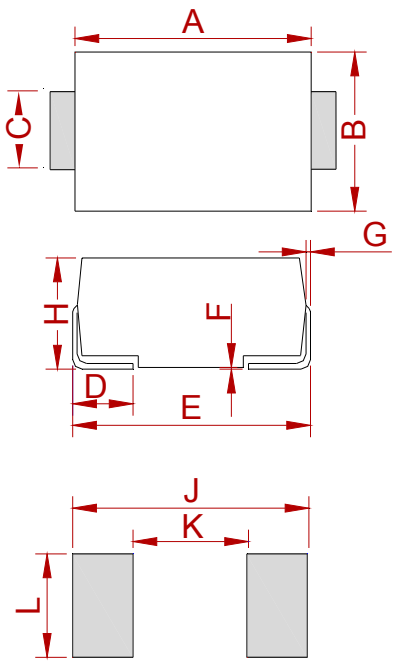


FIG.5 - TYPICAL REVERSE CHARACTERISTICS



PACKAGE MECHANICAL DATA



DO-214AC (SMA)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

REEL SPECIFICATION

P/N	PKG	QTY
SM320A-MS THRU SM3100A-MS	SMA(DO-214AC)	7500

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